ATA, Advanced Technology Attachment VLSI, very large scale integration Flit, flow control unit IC, integrated circuit 集成电路 高级技术附件 MIN, multistage interconnection network SATA, Serial ATA, 串行高级技术附件 HPC, high performance computer IDC, Internet data center SCSI, Small Computer System Interface UPS, uninterruptable power supply SAS . Serial Attached SCSI PDU, power distribution units FC, Fiber Channel, 光纤信道协议 TCO, total cost of ownership JBOD, Just a bunch of disks CapEx, capital expenditure 资本支出 RAID, redundant array of inexpensive drives OpEx, operational expenditure 运营开销 ECC, Error correcting coding, 错误校验码 DAS, Direct Access Storage, 直接存取存储器 NAS, Network Attached Storage 网络附属存储 ISA. instruction set architecture SAN, Storage Area Network, 存储区域网络 CISC, complex instruction set computer RISC, reduced instruction set computer NAND Flash cell PC, program count SLC, single-level cell GPR, general-purpose register 通用寄存器 MLC, multi-level cell SPR, special-purpose register SSD, Solid-State Drive ILP, instruction-level parallelism WA, Write amplification uOps, micro-ops CPI, Clock cycle Per Instruction RAW, read after write PCA, Principal Component Analysis 主成分分析 NTT, normalized turnaround time WAR, write after read WAW, write after write ANTT, average NTT FU, function unit DFS, IF, instruction fetch SISD, Single Instruction Single Data ID, instruction decode SIMD, Single Instruction Multiple Data RO, read operands MISD, Multiple Instruction Single Data EX, execution MIMD, Multiple Instruction Multiple Data WR, write result UMA架构, Centralized Shared-Memory RS, reservation station SMP, symmetric multiprocessors, 对称多处理器 NUMA架构, DSM, Distributed Shared-Memory CDB, common data bus MSI, MESI IPC, instruction per cycle VLIW, very long instruction word TLP, thread-level parallelism CMP, Chip Multi-Processor, 片上多处理器 DB, dispatch buffer BHT, branch history tables SMT,simultaneous multithreading,超线程 BTB, branch target buffer LLC, Last Level Cache MTTF, mean time to failure BIA. branch instruction address MIC、Intel Many Integrated Core 架构 BTA, branch target address SCC, Intel Single-Chip Cloud Computer MTBF, mean time between failure OoO, out-of-order execution MTTR, mean time to repair ROB, reorder buffer DLP, Data-level parallelism, 数据级并行 ACE. Architecturally correct execution EPIC, explicitly parallel instruction computing MVL, maximum vector length AVF, architectural vulnerability factor VLR, Vector Length Register PSU, PTE, page table entry GPU, Graphics processing unit GPGPU, general-purpose computation on GPU MMU, memory management unit VPN, virtual page number GPU上的通用计算 PPN, physical page number SPMD, Single Program Multiple Data 3C model, compulsory/capacity/conflict miss SIMT. Single Instruction Multiple Thread DIMM, dual in-line memory module CUDA, Stands for Compute Unified Device MC, memory controller Architecture TPC, texture/processor clusters RAS, row access table CAS, column access table SM, streaming multiprocessors, 流多处理器 SDRAM, synchronous DRAMS SP, streaming processor, 流处理器

GPC, Graphics Processor Clusters,

图形处理器集群

RF, Register File

DDR, double data rate SDRAM IPM, instruction per miss

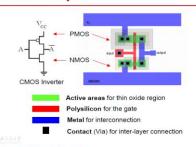
MLP, memory-level parallelism

ICT, information and communication technology WSC, warehouse-scale machine PUE, power usage effectiveness WUE, water usage effectiveness CUE, carbon usage effectiveness ATS, automatic transfer switch STS, static transfer switch equipment UPS, uninterruptable power supply PDU, power distribution unit PSU, power supply unit CRAC, computer room air conditioning COP系数, coefficient of performance TOR, top of rack EOR, end of rack MDA, main distribution area HAD, horizontal distribution area EDA, equipment distribution area SLA, service level agreement DVFS, dynamic voltage and frequency scale MDC, modular data center ACPI, advanced configuration and power interface TDP, thermal design power D2D, die to die C2C, core to core MPP, maximal power point PTP, performance time product TPR, throughput power ratio ROI, return on investment

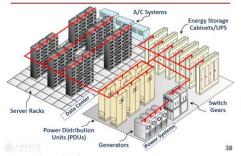
Summary 1	Summary 5	Summary 10
- What is Computer Architecture	- Memory hierarchy, uncore and off-chip	- Throughput computing and data-level parallelism
- History of IC(integrated circuit)	- Cache line, block, address	- Vector processor and vector instruction
- Transistor basics	- Virtual memory, page table, PTE, TLB	- VMIPS, vector registers, DAXPY, execution latency
- Feature length	- Locality principle, Inclusive and exclusive	- SIMD lanes, chaining, vector length register
- HPC vs IDC	relationship	- GPGPU, SIMT, CUDA programming model
- Scale up/out	- Miss caching, victim caching, prefetching	- TPC, SM, SP, warp and warp scheduling
- Energy/power issues	- Cache write policies, write buffer/cache	- Branch divergence
- The trend of Computer	- rank, bank, array, channel, MC,	- GPU register file
Architecture research	parallelism in DRAM	of o register file
Architecture research	- 1T1C DRAM cell, data access, DRAM refresh	Summary 11
Summary 2	- DRAM access cost	- basic concepts, link/channel/buffer
- Architecture vs microarchitecture	- synchronous/asynchronous design	- switch degree, average distance
- Evolution of instruction set	- Memory design challenges, memory wall	- non-blocking network, direct/indirect network
- CISC(IA32) vs RISC(MIPS)	- MLP	- network performance, latency estimation
- Machine interfaces: ISA	- IVILI	- network switch and switch strategy
- User/System ISA	Summary 6	- bus and crossbar
- MIPS instruction field	·	
	- Disk concept; platter/track/sector	- array ring mesh torus tree butterfly hypercube
- Single-cycle MIPS	- Design good drive Interfaces	Summary 12
- Ideal pipeline	- Parallel/Serial ATA; Parallel/Serial SCSI	Summary 12
- Stage quantization	- RAID Organization	- what is a data center
- Pipeline slot	- DAS, NAS, SAN	- major metrics of data center design
S.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	- Flash memory cell, SLC/MLC	- data center infrastructure
Summary 3	- SSD advantages, hybrid storage	- the long tail concept
- Pipeline stall and bubble		- data center capacity utilization
- Dependency and hazards	Summary 7	- types of power provisioning
- RAW, WAR, WAW	- Amdahl's Law	- modular data center and cooling
- Forwarding and pipeline interlock	- Calculating CPI (公式)	
- Functional units	- Analyzing memory access time (公式)	Summary 13
- Dynamic scheduling and OoO	- Little's Law	- G-States, S-States, C-States, P-States
- Scoreboarding	- Estimating server power	- TDP, Turbo Boost
- Tomasulo's Algorithm	- Trace-/Execution- driven simulation- Simulation acceleration	- Power management can be challenging
Summary 4	- Concepts of workload characterization	Summary 14
- Superscalar Pipeline	- Multi-programmed workload	- Faults, error, and failure
- Limitations of scalar processor	, 0	- MTTF, MTBF, MTTR
- Basic feature of superscalar pipeline	Summary 8	- Availability, reliability
- Multi-Issue Processor	- SIMD, MIMD, TLP	- ACE, AVF
- Dispatch Buffer and Completion Buffer	- Multiprocessors, UMA and NUMA	- Redundancy
- Classification of ILP Machines	- Definition of cache coherency	,
- Rationale of branch prediction	- Cache coherency and memory consistency	
- 2-bit prediction	- Basic facts of the snooping protocol	
- Speculation	- A simple write-through invalidation protocol	
- Precise exception: in-order completion	- 3-state MSI protocol	
- Reorder buffer (ROB)	,	
- Tomasulo's Algorithm with ROB	Summary 9	
- VLIW and EPIC	- Thread, Multithreading, SMT	
- CISC vs RISC vs VLIM	- CMP and multicore	
- Loop unrolling	- Benefits of multicore	
- The concept of EPIC	- Multicore system architecture	
·	- Heterogeneous multicore system	
	- Heterogeneous-ISA CMP	
	- Multicore and manycore	

- Design challenge

From Circuit to Layout

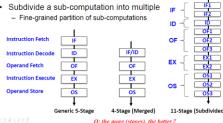


A Typical Data Center



Stage Quantization

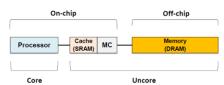
- Merge multiple sub-computations into one
 - Combining sub-computations with short latencies



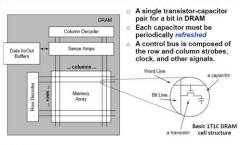
Architecture Comparison

Category	cisc	RISC	VLIW	
Inst Size	Varies	Fixed (typically 32bits	Fixed	
Inst Format	Field placement varies	Regular, consister	t placement of fields	
Inst Semantics	Complex; possibly many dependent ops per instr	Almost always one simple operation	Multiple, independent simple operations	
Registers	Few, sometimes special	Many, gen	eral purpose	
Memory	Reg-Mem architecture	Load/Store	architecture	
Hardware	Exploit microcode	Not microcode	d implementation	
Example:				

Basic Concepts



1T1C DRAM Cell



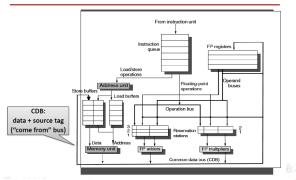
Simulation Approach Comparison

	Function Simulation	Trace-Driven Simulation	Execution-Driven Simulation
Development Time	Excellent	Poor	Very Poor
Evaluation Time	Good	Poor	Very Poor
Accuracy	Excellent	Very good	Excellent
Coverage	Poor	Excellent	Excellent

Full system simulation

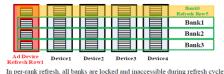
- Trace-driven simulation and execution-driven simulation

Basic Structure Implementing Tomasulo's Alg.



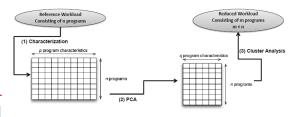
Refresh Mechanism

- A Row is the smallest refresh unit in bank
- Typically, the retention time of data in DRAM cell is 64ms if the nbient temperature is less than 85 degree Celsius
- Refresh operation can implement at rank level (per-rank refresh) or at bank level (per-bank refresh)



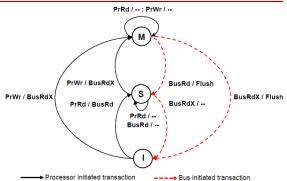
Workload Design (Cont'd)

· Determine a reduced but representative workload

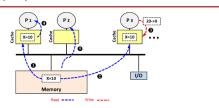


Schematic overview of the PCA-based workload reduction method

A 3-state (MSI) Write-Back Invalidation Protocol



A 3-state (MSI) Write-Back Invalidation Protocol



Processor Action	State in P1	State in P2	State in P3	Bus Action	Data Supplied By
1. P1 reads x	S	-	-	BusRd	Memory
2. P3 reads x	S	-	S	BusRd	Memory
3. P3 writes x	1	-	M	BusRdx	Memory
4. P1 reads x	S	-	S	BusRd	P3 Cache
5. P2 reads x	S	S	S	BusRd	Memory

Calculating CPI

$$CPI = \sum \frac{IC_i \times CPI_i}{Instruction\ count}$$

 $\textit{CPU time} = (\sum \textit{IC}_i \times \textit{CPI}_i) \times \textit{Clock cycle time}$

Example:

Suppose we have made the following measures: Frequency of FP operations = 25% Average CPI of FP operations = 4.0 Average CPI of other instructions = 1.33

CPI original = $(4 \times 25\%)+(1.33 \times 75\%) = 2.0$

Memory Performance Analysis

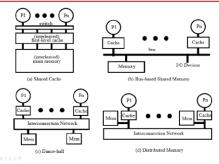
$$\frac{\textit{Misses}}{\textit{Instruction}} = \textit{Miss rate} \times \frac{\textit{Memory accesses}}{\textit{Instruction}}$$

Average memory access time = Hit time + Miss rate × Miss Penalty

Average memory access time = Hit time $_{L1}$ + Miss rate $_{L1}$ imes Miss Penalty $_{L1}$

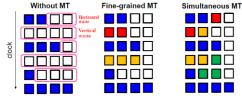
 $Miss Penalty_{L1}$ = $Hit time_{L2} + Miss rate_{L2} \times Miss Penalty_{L2}$

Common Memory Hierarchies in Multiprocessors



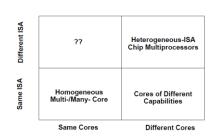
Impacts of SMT on Utilization

Multithreaded processor improves hardware utilization in different dimensions



Thread 1 Thread 2 Thread 3 Thread 4

Classification of Heterogeneous Multicore

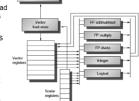


Case Study: VMIPS

- Vector registers
 - 64-element register
 - Register file has 16 read ports and 8 write ports

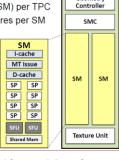


- 5 fully pipelined FUs
- Hazards detection
- · Vector load-store unit
- Loads/stores a vector - 1 word per clock cycle



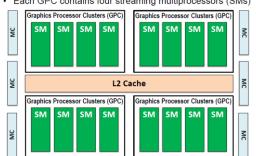
Case Study: Tesla GPU Architecture

- 8 texture/processor clusters (TPCs)
- 2 streaming multiprocessors (SM) per TPC
- 8 streaming processor (SP) cores per SM
- SM is a unified graphics and computing engine
 - SM executes thread blocks
- Streaming processor (SP)
- Scalar ALU for a single CUDA thread
- SP core is a SIMD lane



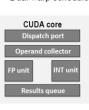
Case Study: Fermi GF100 Architectural Overview

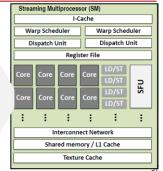
· Each GPC contains four streaming multiprocessors (SMs)



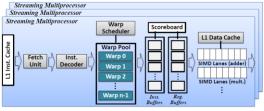
Case Study: Fermi GF100 Architectural Overview

- A single SM contains 32 CUDA cores
- Dual warp scheduler





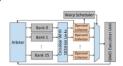
Warp Scheduling (Cont'd)



- Potential factors that can delay a warp's execution
 - Scheduling policies
 - Instruction/Data cache miss
 - Structural/Control/Data hazard
- Synchronization primitives

Resource Limits

- The maximum parallelism in GPUs is often limited by the register file capacity
 - Applications with high TLP triggers more active warps
- Register file is a large SRAM structure
 - Fastest memory block available to the processor
 - Store intermediate results from units such as ALU
 - Power hungry structure



Hypercube (Optional)

- Also known as binary d-cubes $N=2^d$
- Switch degree equals dimension: $d = \log_2 N$
- Good bisection bandwidth
- k-ary d-cube is a d dimensional torus with k elements along each dimension: $N = k^d$
 - Each node is addressed by a d-vector



Performance Evaluation

- Link width: w
- Unit interval: τ
- Signaling rate: f=1/τ
- Channel bandwidth: $b = w \cdot f$
- Total bandwidth of all the channels (or links) the number of channels times the bandwidth per channel

Latency (Lower Bound)

- Sending overhead: Overhead,
- Receiving overhead:
- Total routing time:
- Arbitration time:
- · Switching time:
- Total time of flight of the packet T_{TotalProp}

Latency = $Overhead_s + (T_{TotalProp} + T_R + T_A + T_S) + \frac{Packet \, size}{Bandwidth} + Overhead_r$

Crossbar

- Crossbar switch
 - A type of fully-connected network
 - Every node connected to all others
 - O(N) bandwidth
 - Cost of interconnect: O(N^2)
 - Good for small number of nodes



- Crosspoint switch complexity increases quadratically with the number of ports
- · Multistage interconnection networks reduces complexity

Multidimensional Topology: 2D Torus

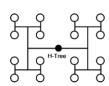
- · Reduces the diameter of a mesh network
- · Torus: adding end-round direct connections
 - An extension of the 2D mesh
 - A regular torus has long warp-around links
- Slightly lower latency while higher cost





Trees (Optional)

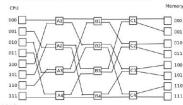
- Trees features planar, hierarchical topology
- Employed as indirect networks with hosts as leaves
- Routing distance grows only logarithmically



Multistage Interconnection Network (Optional)

- · Indirect networks with multiple layers of switches
- Omega network:

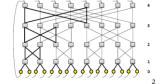
Log(N) number of stages and N/2 switching units



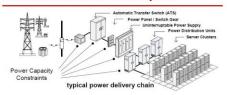
Butterfly Topology (Optional)

- Butterfly is an important logarithmic network
- Can be viewed as a tree with multiple roots
- A d-dimensional indirect butterfly:
- Connects $N = 2^d$ nodes $(d \ge 2)$ $d = \log_2 N$ levels of switches



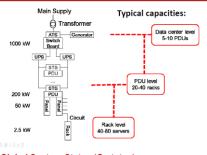


Datacenter Infrastructure - Power System



- ATS: basically a fast, mechanical switch
- STS: basically a superfast, electronic switch
- UPS: basically a battery with control interfaces
- PDU: a power converter and distribution unit

Datacenter Infrastructure - Power System



Global System States (G-states)

G-states are high-level description of the platform states

- G0 (working)
 - The working system state
- G1 (sleeping)
 - No computational task is performed
- G2 (soft off)
 - Powered down but can be restarted by interrupts
- G3 (hard off)
- Sleep States (S-states)

S-states are set in the BIOS and configured by the system

- · G0-S0: normal operation
- G1
 - S1: processor clock is off
- S2: processor is off
- S3: suspend to RAM S4: suspend to disk
- G2-S5: halt state

Processor Power States (C-states)

G0 and S0 together define a working platform state, at which a range of C-states are defined to save power

- C0 State (normal operating state)
- code is being executed
- C1 State (auto halt):
- The clock is gated, i.e., prevented from reaching the core
- C3 State (sleep):
- Maintains architectural state but flushes data to shared LLC
- Shut down the clock generators

- Architectural states are saved to a dedicated SRAM - Core voltage reduced to zero volts

Processor Performance State (P-states)

P-States talk about different operational modes (freq.)

- · Multiple levels of clock frequency
- From P0 (the highest performance) to Pn (the lowest performance) Sub states of C0
- Defines dynamic voltage and frequency scaling (DVFS) steps · Switching latencies are negligible for most purposes

Voltage	P-State
1.484 V	P0
1.420 V	P1
1.276 V	P2
1.164 V	P3
1.036 V	P4
	1.484 V 1.420 V 1.276 V 1.164 V

Intel Pentium M at 1 6GHz **Tracking Coordination**

. Move load I-V curve to MPF

- Tune the multi-core processor



MPPT position can be tricky: LEFT side or RIGHT side?